3.7.1 Number of collaborative activities with other institutions/ research establishment/industry for research and academic development of faculty

3.7.1.1: Total number of Collaborative activities with other institutions/ research establishment/industry for research and academic development of

SI. No.	Title of the collaborative activity	Name of the collaborating agency with contact	Name of the participant	Year of collaboratio	Duration	Nature of the activity	Link to the relavant document
1	BrightGeeks	BrightGeeks 9441188123 info@brightgeeks.in www.brightgeeks.in Marathahalli ORR,Bengaluru ,Karnataka		Jan-23	Continuing- Until either of the parties terminated	Providing Industrial visit, Guest Lecturer, Placement of trained students.	https://drive.goo gle.com/drive/fol ders/1gUrbUkzyv mrPLfORoAB9AK PPeDegF4IB
2	Excel-R	Excel-R ExcelR EdTech Private Ltd. enquiry@excelr.co m www.excelr.com 49,1st cross,27th main BTM Layout, Bengaluru		Dec-23	Continuing- Until either of the parties terminated	Student Develoment Programs, FDPs and Ionternships on different emerging Software Technologies.	https://drive.goo gle.com/drive/fol ders/1gUrbUkzyv mrPLfORoAB9AK PPeDegF4IB
3	IEEE Hyderabad Section - Skill Connect program	IEEE Hyderabad Section - Skill Connect program The Secretary, IEEE Hyderabad Section #644-645, Al Karim Trade Center Secunderabad, Telangana, India -		Sep-21	Sep-23	Skill deveopment through workshops,Copnferen ces and seminars	https://drive.goo gle.com/drive/fol ders/1gUrbUkzyv mrPLfORoAB9AK PPeDegF4IB
1			GURRAMKONDA KISHORE				
2			KATARI HARI PRASAD N SAI HARIKA				

4]		NYNARU TEJA				
5			NEDAMBARAM SNEHA				
6	-		NEELAM AJAY				
7			CHAPATI CHARITHA				
— ′	-		KALLURI SAI				
8			DEEKSHITHA				
9	1		GUDIPATI PUNEETH				
10	†		VYASAVA PREETHI				
	1		AKKUPALLI LALITHA				
11			SREE				
12	1		NAMBURI SAI				
12			PRANEETH				
13			KALLAPATI SOWMYA				
14]		KAAVALI BHEEMESH				
15			JADAV KHUSWANTH				
15			RAO				
16			BOMMI CHETHAN				
17			MADDIPATLA				
			VENKATA SAI				
18			VITTA SAI BALAJI				
19		Entuple	KURUBA PRANATHI				
20		·	CHENNAMSETTY JAYA				
	<u> </u>	Technologies Pvt.	LAKSHMI				
21	Five day workshop	Ltd, No. 211, Outer					
22	on VLSI Circuit	Ring Road,	THATHURU LIKHITHA	2023	Five days	Hands on Training	
23	Design	East of NGEF	ALLAM SANDEEP				
24		Layout, Kasturi	JINKA PRIYANKA				
	 	Nagar,	KEERTHI				
25		Bengaluru	NARASAPURAM				
—	-		YASWANTH PATHIPATI				
26			PRAVALLIKA				
27	†		MIDDE MANJUNATH				
28	-		RASAPALLI AKASH				
	1		BODDULURU UDAY				
29			KIRAN				
	4	I		l	I	I	ı

30		KOTHAPALLI			
		VYSHNAVI			
31		PODHIGARI NIHARIKA			
32		DODDI NAVEEN			
33		POLICHERLA			
		HEMALATHA			
34		POLISETTY MANASA			
35		JANGA VENKATESWAR REDDY			
36	1	SEELAM JYOTHIRMAI			
		GOKARAJULA			
37		PUNEETH SAI			
		IPPAGUNTA VENKATA			
38		SAI SREE CHANDANA			
39		G SRAVANI			
40		SOMISETTY SAI			
		DEEKSHITHA			
41		Dr. K Upendra			
		Raju			
42		Mr A Krishna			
		Mohan			
43		Mr P Srinivasulu			
44		Mrs M Poornima			
45		Mrs M Sharmila			
46		Mr M Vasudeva			
40		Reddy			
47		Mrs C Rajani			
48		Mr P Suresh Babu			
40]	Mr SVS Jaya			
49		Shyam			
F.0		Mr K M			
50		Manjunath			
	•			•	•

51			Mr SK Allabaksh			
52			Mr K Yuvaraj			
F.2		_	Mrs T Swarna			
53		Entuple	Latha			
F.4	One week Faculty	Technologies Pvt.	Mr E Anant			
54	development on	Ltd, No. 211, Outer	Shankar			
55	"VLSI Circuit Design	Ring Road, East of NGEF	Mr P Rajesh	2023	One Week	Workshop
	using Cadence	Layout, Kasturi	Mr N Gunasekhar			
56	Tools"	Nagar,				
		Bengaluru	Reddy			
57		201.601010	Mrs P Sai Kusuma			
57			IVII S F Sai Kusuilla			
58			Mrs B Chandrakala			
59			Mr V Nagendra			
			Kumar			
60			Mr M Mahesh			
61			Mrs CH Pallavi			
62			Mrs KVL Keerthi			
63			Mrs M Kalpana			
64			Ms D Srilatha			
65			Ms B Deepa			
66	•		Mr K R Surendra			
67			Mr G Naveen			
	•		Kumar			
68	•		Mr S Mohan Rao			
69			Mrs P Aruna			
			Kumari			
70			Mrs K Amala			
71			KAYALA IMMANUEL			
72			PARNA USHA SREE			
/ 4			I ANNA OSHA SINLE			1

72			PILARIKUPPAM				1
73			CHANDANA				
74			SAGI RISHITHA				
75			GURRAMKONDA				
/5			ABZAL				
76			KRITHIKA C				
77			TIKKAM DHILIP				
//			KUMAR REDDY				
78			KONDURU SIVA				
			KUMAR				
79			C SURESH KUMAR				
80			PALLAPU THARUN				
81			SUGALI BHARATH RAJ				
01			NAIK				
82			GANDHAM PREM				
			KUMAR				
83			B SRAVAN KUMAR				
84			BURAKALA PAVITHRA				
85			PANDHITI HEMANTH				
86			AMARCHAND KISHORE				
			KUMAR				
87			ENDLURU SWETHA				
88			KURUBA MANJUNATH				
			VALLUVAN				
89			MAHESWARAN				
90	Five day workshop	'	MANIMALA VYSHNAVI				
91	on Digital Image Processing	of Electrical Engineers,	NELLORE BHANU SREE	2023	Five days	Workshop	
92	Techniques	Hyderabad	NATUKULA KAIVALYA				
93	•	· ·	PAIDALA ASHA				
			SREEMANTHULA				
94			YUVASREE				
95			C GNANADEEP REDDY				
96			VATTIVELLA CHANDU				
97			B KAVYA				
	1	1			I	I	I

98	RUDRARAJU SANJAY		
98	KUMAR RAJU		
99	JABBALA ARUN		
33	KUMAR		
100	BOLLAVARAM NAGA		
	MAHESWAR REDDY		
101	KOPPOLU KUSUMA		
102	GADI MAHATHI		
	PRATHIMA		
103	VELLORE CHANDRIKA		
104	BODUGU GURU		
104	CHARAN YADAV		
105	THANDRA YUGESH		
106	RAYAPU REDDY		
100	YASHODA		
107	VENKATA RANGA SAI		
107	KARTHIK KOTHA		
108	SARUKOLLA GURU		
100	HEMANTH		
109	DASARARAJU		
	JASWANTH		
110	GAJJALA RANJITH		
	REDDY ERAGAPPAGARI		
111	SIREESHA		
112	TARIPILI SEKHAR		
113	KUPPA KAVYA		
114	GURRAM DEDEEPYA		
115	VADDI DIMPUL REDDY		
116	MUDE SAI RAMYA		
117	SYED SANA FATHIMA		
	KODURU BHAVYA		
118	SREE		
110	GULURU PAVAN		
119	KALYAN		
120	MADITHETI SULEMAN		

	1		KUNTRAPAKU VAMSI			1
121			KRISHNA			
122			SUNKU VINAY			
123			GOWTHAM S			
			SEGIJI SRAVAN MUNI			
124			KUMAR			
125	1		BAYANABOINA			
125			DEVENDRA			
126			POCHAMREDDY			
120			LOHITHA			
127			AKULETI MURALIDHAR			
128			RAMALINGAM SUNEEL			
			KUMAR			
129			P N SRAVANI			
130	Five day workshop	Cri Chachua Dravathi	SIRIGIRI SIREESHA			
131	on Signal Processing	Sri Shashya Prayathi	1117(22) (17(22) \$7(10)(2)(1)	2022	er . J	Maril de c
131	Techniques Using	Technologies Pvt.	REDDY	2023	Five days	Workshop
132	MATLAB	Ltd., NITK-STEP	AKULA MOUNIKA			
	-		REDDY PANTRANGAM			
133			THIRUMALA			
134	1		VALLUTHUR GANESH			
135			T CHIRANJEEVI			
155	-		BELLAM SANATH			
136			KUMAR			
			PALAMANI			
137			BHANUPRASAD			
138	1		POTHURAJU SAI			
138			SOWMYA			
139			AVULA SRINIVASA			
			ANIRUDH			
140			C LAVANYA SREE			
141			MOPURI THANUJA			
142			PULLAGURA			
	-		JASWANTH YADAV			
143			VIDYALAVARU			
144	1		SUBHASH REDDY			
144]		POTHALA ISWARYA			1

146 147 148 149 150 KANAGANI SAI KALYANI DESHMUKH SUMAIYA KHAN MAMILLA MADHU KOTTAMIDDE MAHENDRA TIRUMANDYAM SOMA SEKHAR REDDY	145	CHITTULURI SREYA
147 148 149 150 147 148 TIRUMANDYAM SOMA	146	KANAGANI SAI
147 148 149 KHAN MAMILLA MADHU KOTTAMIDDE MAHENDRA TIRUMANDYAM SOMA	140	KALYANI
148 149 KHAN MAMILLA MADHU KOTTAMIDDE MAHENDRA TIRUMANDYAM SOMA	1/17	DESHMUKH SUMAIYA
149 KOTTAMIDDE MAHENDRA TIRUMANDYAM SOMA	147	KHAN
149 MAHENDRA TIRUMANDYAM SOMA	148	MAMILLA MADHU
150 MAHENDRA TIRUMANDYAM SOMA	140	KOTTAMIDDE
l 150 l l l	149	MAHENDRA
l 150 l l l		TIRUMANDYAM SOMA
	150	SEKHAR REDDY





Memorandum of Understanding (MoU) for Industry Academia Collaboration

This Memorandum of Understanding ("MOU") for general cooperation is entered into an effective as of 03-08-2021 by and between:

Entuple Technologies Pvt. Ltd., having its registered office at #2730, Trikannika, 80 Feet Road, Opp. C M H Hospital, HAL III Stage, Indiranagar, Bangalore - 560038. hereinafter referred to as "COMPANY", which expression shall, unless it is repugnant to the context thereof be deemed to include all its successors and assignees represented by its board of Directors of the FIRST PARTY.

AND

Sri Venkateswara College Of Engineering, an Educational Institution registered under the Council for Social Development Society and having its office at, Karkambadi road, opposite to LIC Training Centre Tirupati, Andhra Pradesh-517 507, and represented by its authorized signatory Director/Principal, Dr. N. Sudhakar Reddy herein after referred to as "SVCE" hereinafter referred to as "INSTITUTION" which expression shall, unless it is repugnant to the context thereof be deemed to include its successors and assignees represented by its Registrar of the SECOND PARTY.

COMPANY AND INSTITUTION shall hereinafter be individually referred to as "Party" and collectively referred to as the "Parties"

Now, therefore this MoU witnesses:

I - PURPOSE

Entuple & S.V.College of Engineering hereby establish this memorandum of understanding (MOU) to express their desire to work together in areas of skill development and capacity building activities for students, faculty.



Duch





Entuple & S.V.College of Engineering wish to explore a mutual beneficial relationship to:

- Facilitating Industry and Academia interactions for the benefit of upskilling faculty on a regular basis and ensure they impart the relevant technology foundation and application skill to students using the appropriate teaching methodology, tools and infrastructure time to time.
- Drive skill development focused value-added courses, job-oriented courses to students to assist them to acquire the skill desired by industry
- Providing industry relevant project ideas for student projects
- Providing industry relevant R & D project ideas for faculty projects

II - ROLES AND RESPONSIBILITIES

This MOU sets forth the general roles and responsibilities that the parties propose to follow as they cooperate in the exchange of information in order to collaborate further in the areas which are mutually beneficial to the charter and mission of both Entuple & S.V.College of Engineering.

The broad areas of engagement that have been identified as part of this general cooperation agreement are:

- A. Entuple & S.V.College of Engineering will endeavor to set a joint agenda on an annual basis in aid of implementing the purpose
- B. Entuple will work with S.V.Gollege of Engineering as Industry Partner for competency/skill development activities

COMPANY Responsibilities:

- A. ENTUPLE to support S.V.College of Engineering has Industry Partner in VLSI Design, RF and Antenna Design, Electronic Circuit Design and Simulation, Electromagnetics & Electro-Magnetics System Analysis and IoT System design and allied areas of mutual interest.
- B. Entuple to support S.V.College of Engineering in framing/upgrading curriculum in the defined technology as industry partner.



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- C. Entuple to support short term courses/ training cum internship programs and/or Career Builder Programs for students to increase awareness on VLSI Design, RF and Antenna Design, Electronic Circuit Design and Simulation, Electromagnetics & Electro-Magnetics System Analysis and IoT System design and allied technologies.
- D. The duration, schedule, commercials, and revenue sharing of all training programs are jointly devised by COMPANY AND S.V.College of Engineering.

INSTITUTION Responsibilities:

- 1. S.V.College of Engineering to upgrade curriculum as per the inputs from INDUSTRY partner and implement the same in delivery of courses in the curriculum
- 2. S.V.College of Engineering to be responsible for providing Hardware PCs & networking, basic Operating systems software & pertinent equipment & software required for FDP/Short Term Courses & Training cum Internship Programs at campus
- 3. S.V.College of Engineering to encourage faculty and students to actively participate in FDP and training programs driven jointly.
- 4. S.V.College of Engineering shall drive minimum batch size and number of programs per annum as per mutually agreed terms and conditions
- S.V.College of Engineering shall designate a faculty coordinator for all training programs to coordinate with COMPANY in scheduling, execution of all training programs
- 6. S.V.College of Engineering shall make payment to the COMPANY the training charges as per mutually agreed terms & conditions



IV Training Programs focused on Skill Enhancement

Training Programs focused on Skill Enhancement & mode delivery supported





a. Short Term Courses (Online/Classroom) - Upto 5 days-

Classroom training is supported at campus

b. Training cum Internship Programs for students (Online and Classroom): Upto 4 weeks

Classroom training is supported at campus

c. Career Builder Programs (Online/Classroom): Upto 4 months Classroom delivery only at Entuple Technologies, Bangalore

V Activities Benefitting Host institution under MoU

- 1) S.V.College of Engineering can conduct free Webinar/workshop in association with Entuple technologies as per mutually agreed schedules and mode of operandi
- 2) S.V.College of Engineering can conduct paid Faculty Development Program (FDP), Short Term Training Programs (STTP), Training cum Internship Program, Career Builder Programs in association with Entuple. These programs are aimed at providing industry skills in campus and boost competency and employability of students.
- 3) The cost of all training programs is decided mutually by INSTITUTION & COMPANY.
- 4) Under this MoU S.V.College of Engineering & Entuple agree for a revenue share of 30:70 respectively for all training programs jointly driven under mutually agreed terms & conditions
- 5) The minimum batch size for all training programs and number of batches per annum as per mutually agreed terms and conditions.
- 6) All training programs cost is subject to level of complexity and expertise level as per the discretion of Entuple
- 7) All the training information will be sent to the mail id given by the institution.
- 8) Entuple shall support one day Career guidance program every year either onsite or online
- 9) Special discounted price for Virtual Lab options supported by Entuple technologies.
- 10) Two faculty can avail free entry for selected programs under this MoU
- 11) Entuple technical team will provide support for institution in forming the curriculum and upgrade

12) COMPANY shall accommodate students from S.V.College of Engineering for industrial visits and technical discussions at a mutually agreed terms and conditions. The field visits to serve the industrial exposure to faculty and students of S.V.College of Engineering





VI - INTELLETUAL PROPERTY

a. The term "intellectual property" as used herein means all intellectual property, whether or not capable of being registered, including but not limited to patents, copyright, computer software, code, design, chip technology rights, mask works, trade secrets, know how technique, methodologies, trademark, service mark, logo, trade name and corporate names.

b. It is hereby expressly clarified that any intellectual property independently created by S.V.College of Engineering /its faculty/Student at the Entuple center for excellence which is not derived from and does not embody Entuple intellectual property or Entuple confidential information shall vest solely with S.V.College of Engineering, and Entuple shall not be entitled to the same unless and until specifically agreed upon prior to or during the engagement.

VII - RELATIONSHIP

S.V.College of Engineering understands and acknowledges that its relationship with COMPANY or its affiliate will be that of an independent principal and nothing in this agreement is intended to or should be construed to create a partnership, joint venture, agency or employer-employee relationship and neither party shall have any authority of the other otherwise than as strictly provided herein

VIII - TERMS AND TERMINATION

- 1) This MoU shall become effective from the date hereof and shall remain in force unless terminated in accordance with provisions for a duration of 3 years.
- 2) Entuple and S.V.College of Engineering may extend the areas of collaboration on mutual discussion, agreeable terms, and conditions time to time.
- 3) Institution shall be provided by a unique id and students needs to enter the ID number while making the payment for any of the programs conducted/supported by Entuple



- 4) All programs should be published in S.V.College of Engineering website and social media channels/notice board or through email or other channels of communication to all students all times.
- 5) The MOU shall be renewed for the consecutive year only if Minimum number of training programs with agreed batch size is facilitated by S.V.College of Engineering and executed by INDUSTRY at mutually agreed terms and conditions
- 6) The MOU shall be renewed after every two years.





- 7) This MoU may be terminated by either party hereto if another party commits material breach or default in performance of its obligations hereunder and the same (if capable of being remedied), has not been cured within 30 (thirty) days of receipt of written notice of such breach or default.
- 8) In case of termination of agreement by S.V.College of Engineering, the institution is obliged to give an undertaking stating that any part of training content IP including source content, illustrations, design case studies will not be used/reproduced in any format without prior written permission for any training related activities the institution might choose to offer and execute either independently or in collaboration with any other 3rd party. Violation of this may warrant legal implications subject to the discretion of Entuple Technologies Private Limited, Bangalore.
- 9) The termination hereof shall not serve to release a Party from the performance of such of its obligations as may have arisen prior to termination.

In WITNESS WHEREOF, the Parties have caused this MOU to be signed by their duly authorized representatives as of the MOU effective date above.

WITNESSES:

For S.V.College of Engineering

Name: Dr.N. SUDHAKAR REJDY Designation: PRINCIPAL

Signature:

Date:

For Entuple Technologies Pvt. Ltd.

Name: Mehta S D - Director Sales

Designation:

Signature: _____

Date:







MEMORANDUM OF UNDERSTANDING

HYDERABAD INSTITUTE OF ELECTRICAL ENGINEERS (HIEE)

AND

SRI VENKATESWARA COLLEGE OF ENGINEERING (SVCE)

This Memorandum of Understanding (MoU) establishes a type of partnership between **HIEE** and **SVCE**.

I. MISSION:

Hyderabad Institute of Electrical Engineers (HIEE) an ISO certified Pioneer Finishing School in India for Electrical designing courses, located in Hyderabad. Designed with the intent of bridging the gap between the academics & industry from the year 2010 onwards and trained more than 6000 students as on date.

Sri Venkateswara College of Engineering (SVCE) ensures setting high standards in imparting professional education by employing proven new education methodologies along with the measurable techniques which would help both the faculty & students to make learning a great experience to help them embrace the opportunity suiting them.

The Memorandum of Understanding to promote PLACEMENTS, INTERNSHIPS, WORKSHOP'S AND PROJECTS. Accordingly, HIEE and SVCE operating under this MoU agree as follows:

II. PURPOSE AND SCOPE

HIEE and SVCE describe the intended results or effects that the organizations hope to achieve, and the area(s) that the specific activities will cover.

BENEFITS TO SVCE:

- Job oriented training
- Practical Oriented sessions
- Real time projects
- Industry visits
- Certificates
- Placements
- Workshops and guest lectures
- Internships









BENEFITS TO HIEE-EMPOWERING ENGINEERS:

- This would strengthen our Effort of being the one of the preferred Premier Finishing School in India.
- We are in this Space of Establishing the Connect Between the academics & Industry for over a decade and this role of ours would help us build the careers of the upcoming generation of qualified engineers.
- Develop HIEE as the most desired platform for the Core Engineers serving both the student and industry.

BENEFITS TO THE STUDENTS OF:

- 2nd year students for workshops Industry visits
- 3rd year students for Internship programs and mini projects
- 4th year Final Semester students for Job oriented training with Placements.

Note: All the courses are provided with Certificates.

III.TERMS OF UNDERSTANDING:

The term of this MoU is for a period of 3 years with effect from 09/09/2021. This MoU can be extended upon written mutual agreement. It shall be reviewed annually to ensure that it is fulfilling its purpose and to make any necessary revisions. Either organization may terminate this MoU upon thirty (30) days written notice without penalties or liabilities.

AUTHORIZATION:

The signing of this MoU is not a formal undertaking. It implies that the signatories will strive to reach, to the best of their ability, the objectives stated in the MoU.

On behalf of the organization I represent, I wish to sign this MoU and contribute to its further development.

Note:

- 1. There will be no financial commitments between HIEE and SVCE.
- 2. All the courses are provided with Certificates& few Programs would be on chargeable basis which would be informed to the students directly. Placements are the additional support on a non-chargeable basis.









Partnering organization:

HYDERABAD INSTITUTE OF ELECTRICAL ENGINEERS (HIEE)

GST No: 36AAIFH5036P1ZX

AICTE Organization Reference ID: CORPORATE612f1d8dadeeb1630477709

Name: (Hdan)
Designation: (Managar Morleting)

Date: 09/09/2021.

Your organization:

SRI VENKATESWARA COLLEGE OF ENGINEERING (SVCE)

Name:

Dr. N. SUDHAKAR REDD

M.Tech.,Ph.D.

Designation, COLLEGE OF ENGINEERING TIRUPATI - 517 507

Date: 09/09/2021.



ఆంగ్రజీవేశ్ आंध्र प्रदेश ANDHRA PRADESH SI. No. 799 Bate 19/3/16 Sold to Sri. A. Gangi Reddy Sto. A. Chinna Chanoledly For Whom Sri. The Chairman, S. V. College of Engineering

50AA 498344

K. Vasundhara

K. VASUNDHARA

Licensed Stamp Vendor

L.No: 10-22-017/15

7-1-21/A, R.N.Mada Street

TIRUPATI-517507, Cell No: 0490182747

MEMORANDUM OF UNDERSTANDING (MOU)

This MOU is made and entered into on 5th December 2022 Sri Venkateswara College of Engineering (Here in after referred to as SVCE and M/s. Sri Shasha Prayathi Technologies Pvt. Ltd., (Here in after referred to as SSPT) for the purpose of enriching the technical education process and for continuous interaction between industry and institution.

Sri Venkateswara College of Engineering (SVCE) is a private engineering college established in the year 2007, at Tirupati, Andhra Pradesh. The college is affiliated to Jawaharlal Nehru Technological University and is approved by AICTE. It is an Autonomous Institution. It offers UG & PG courses in the field of Engineering, Management & Computer Applications. The college has state-of-the-art infrastructure and qualified faculties to deliver high-quality technical education

PRINCIPAL

5. %. COLLIGE OF ENGINEERING

BARARAMBAULHOAU

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MEMORANDUM OF UNDERSTANDING BETWEEN SVCE AND SSPT

The SVCE and SSPT, agree to share the information of mutual concern and interest in the following areas.

- > Industrial training and academic projects for students of SVCE by the Engineers of SSPT.
- ➤ Provision of experts and their ideas in Innovation oriented projects and partnerships in areas like Radar Signal Processing, VLSI based Signal Processing, Machine Learning and Deep Learning for Radar System, Millimeter wave radar sensors, Software defined Radios, Arduino based IoT Applications.
- > Short Term Activities of mutual interest including technical consultancy.
- ➤ Long Term Development program on topics of mutual interest.

THE RESPONSIBILITIES OF THE SVCE AND SSPT UNDER THIS MOU ARE DETAILED BELOW

- ➤ The SVCE and SSPT shall extend each other's facilities such as Computers Software, workshops, sophisticated equipments, instruments etc, and library facilities according to rules and regulations of each party as per the conditions laid down by the parties.
- > Engineers of SSPT to serve as faculty to guide in the development programs of mutual interest and conduct of intensive courses.
- Design and Development of curriculum in new areas of Engineering & Technology, particularly with short- and long-term courses in Embedded Systems, VLSI, Radar Signal Processing (MATLAB), Machine Learning and Deep Learning for Radar System, Millimeter wave radar sensors, Software defined Radios, Arduino based IoT Applications which will be beneficial to the students of SVCE. The SSPT has coordination with the faculty of SVCE and R&D Engineers of SSPT in order to bring out good instruction manuals, which will benefit both parties.
- > The Engineers from SSPT will deliver special lectures on the current development, which will be very useful for students to update their knowledge.
- > The procedural aspects and responsibilities of the collaboration will be based on mutually agreed terms. A committee shall be constituted with the members of SVCE faculty and Engineers of SSPT to identify the areas for collaborative programs.

PRINCIPAL S.V. COLLEGE OF ENGINEERING KARAKAMBADI ROAD THRUPATI-517 507, A.P. PS

PERIOD AGREEMENT

This agreement becomes effective on the date of signature and continues for 5 years. It may be modified by mutual consent of both the parties. The agreement may be terminated by any party upon 60 days advance written notice to the other party.

ACCEPTANCE AND APPROVAL OF AUTHORIZING OFFICIALS

Authorized Signatory

N Sudhakar Reddy

Designation: PRINCIPAL Sri Venkateswara College of Engineering (SVCE) Karkambadi Road, **TIRUPATHI - 517 507**

Authorized Signatory

Name: Mr. Yeswanth Pattipati

Designation: Director Sri Shasha Prayathi Technologies Pvt. Ltd Nursery Unit 12(b), NITK-STEP Srinivasnagar P.O., Mangalore Karnataka-575025



Tel: +91-97429 72744 info@takshila-vlsi.com



MEMORANDUM OF UNDERSTANDING (MOU) FOR ACADEMIC COLLABORATION

Between



TAKSHILA INSTITUTE OF VLSI TECHNOLOGIES,

BENGALURU, KARNATAKA

And



SRI VENKATESWARA COLLEGE OF ENGINEERING (AUTONOMOUS), MANGALAM- 517507, ANDHRA PRADESH.

This MOU is entered onto on the 4th day of March 2024 by and between Takshila Institute of VLSI Technologies (hereafter called Takshila VLSI) situated at 2nd Floor, Ram Arcade, 90/1B, CKB Layout, Chandra Layout, Marathahalli, Bengaluru –56/1937, Kakinataka.

Regd. Office: 2nd Floor, Ram Arcade, 90/1B, CKB Layout, Chandra Layout, Marathahallip Bentyohitu, Karnataka 560037, INDIA | GSTIN: 29AAOFT6099G1ZC

Tel: +91-97429 72744 info@takshila-vlsi.com



and

Sri Venkateswara College Of Engineering, (hereafter called college) situated at Mangalam, Andhra Pradesh State to explore a mutual beneficial relationship to:

- **a.** Facilitate Industry and Academia interactions for the benefit of the upskilling faculty on a regular basis and ensure they impart the relavant technology foundation and application skill to students using the appropriate teaching methodology, tools and infrastructure time to time.
- **b.** Drive skill development focused value-added courses, job-oriented courses to students to assist to acquire the skill desired by industry.
- **c.** Provide industry relevant project ideas for student projects.

1. Objectives of MOU

- **d.** To promote and enhance semiconductor / VLSI domain interest in students.
- e. To provide Online/Offline/Weekend training to students in VLSI courses such as Physical Design / Analog Layout /ASIC Verification / Design for Test (DFT).
- **f.** To provide internship to students from VLSI Service provider company SiValley Technologies Pvt. Ltd. in Digital or Analog Domains.
- **g.** To provide placement assistance to the students who complete the course / internship.
- **h.** To provide academic interaction by delivering special lectures at college on topics of relevance to semiconductor domain

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2. Proposed Modes of Collaboration

Takshila VLSI and College to collaborate through the following:

- a. Cooperation and promotion of education and training in areas of mutual interest.
- **b.** Any other appropriate mode of interaction agreed upon between Takshila VLSI & College.

Any specific plan will be worked out by the college depending upon availability of resources.

3. Terms and Conditions

- a. For the visits related to advice & consultancy, travel and other expenses of Takshila VLSI staff shall be reimbursed by College on mutually agreed terms.
- **b.** Usage of College academic infrastructure can be allowed for limited period subject to its availability, approval of Head of the facility/department and college norms.
- **c.** This MOU may be amended, renewed and terminated by mutual written agreement of the *colleges* at any time.
- **d.** Either Takshila VLSI or College shall have the right to terminate this MOU upon 60 days prior written notice to the other.

4. Confidentiality

The Takshila VLSI and the College agree to hold in confidence all information /data which is obtained from either *Takshila VLSI or College* or created during the performance of the MOU and will not disclose the same to any third party without written consent of the other.

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5. Duration of MOU

This MOU, unless extended by mutual written consent of the *both*, shall expire in FIVE years after the effective date. However, on review, the MOU shall be extended for another TWO years by mutual consent.

6. Coordinators

Both Takshila VLSI and College will designate persons who will have responsibility for coordination and implementation of this agreement.

7. Intellectual Property Rights

Intellectual Property Rights (IPR) that arise as a result of joint research and collaborative activity under the agreement will be worked out on a case to be case basis and will be consistent with officially laid down IPR polices both.

8. Signed in Duplicate

The MOU is executed in duplicate with each copy being an official version and having equal legal validity. By signing below, the *Takshila VLSI and College*, acting by their duly authorized officers, have caused this Memorandum of Understanding to be executed, effective as of the day and year first above written.



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On behalf of	On behalf of
TAKSHILA INSTITUTE OF VLSI TECHNOLOGIES	SRI VENKATESWARA COLLEGE OF ENGINEERING(AUTONOMOUS)
For Takshila Institute of VLSI Technologies	Meddy
Authorised Signatory Rajesh K	Dr. N. SUDHAKAR REDDY M.Tech.,Ph.D. PRINCIPAL S.V. COLLEGE OF ENGMEERING KARAKAMBADI ROAD TIRUPATI - 517 507, A.P.
Operations Manager	
Divy Divy ASTOR	Sollede Oktoballing in the Bulyage